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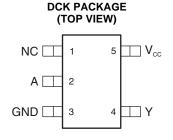
LOW POWER, 1.8/2.5/3.3-V INPUT, 3.3-V CMOS OUTPUT, SINGLE SCHMITT-TRIGGER INVERTER GATE

Check for Samples: SN74AUP1T14

FEATURES

- Single-Supply Voltage Translator
- Output Level Up to Supply V_{CC} CMOS Level
 - 1.8 V to 3.3 V (at $V_{CC} = 3.3 \text{ V}$)
 - 2.5 V to 3.3 V (at $V_{CC} = 3.3 \text{ V}$)
 - 1.8 V to 2.5 V (at $V_{CC} = 2.5 \text{ V}$)
 - 3.3 V to 2.5 V (at $V_{CC} = 2.5 \text{ V}$
- Schmitt-Trigger Inputs Reject Input Noise and Provide Better Output Signal Integrity
- I_{off} Supports Partial Power Down (V_{CC} = 0 V)
- Very Low Static Power Consumption: 0.1 μA
- Very Low Dynamic Power Consumption: 0.9 μA
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Pb-Free Packages Available: SC-70 (DCK)
 2 x 2.1 x 0.65 mm (Height 1.1 mm)

- More Gate Options Available at www.ti.com/littlelogic
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

The SN74AUP1T14 performs the Boolean function $Y = \overline{A}$ with designation for logic-level translation applications with output referenced to supply V_{CC} .

AUP technology is the industry's lowest-power logic technology designed for use in extending battery-life in operating. All input levels that accept 1.8-V LVCMOS signals, while operating from either a single 3.3-V or 2.5-V V_{CC} supply. This product also maintains excellent signal integrity (see Figure 1 and Figure 2).

The wide V_{CC} range of 2.3 V to 3.6 V allows the possibility of switching output level to connect to external controllers or processors.

Schmitt-trigger inputs ($\Delta V_T = 210$ mV between positive and negative input transitions) offer improved noise immunity during switching transitions, which is especially useful on analog mixed-mode designs. Schmitt-trigger inputs reject input noise, ensure integrity of output signals, and allow for slow input signal transition.

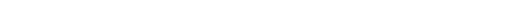
 I_{off} is a feature that allows for powered-down conditions ($V_{CC} = 0$ V) and is important in portable and mobile applications. When $V_{CC} = 0$ V, signals in the range from 0 V to 3.6 V can be applied to the inputs and outputs of the device. No damage occurs to the device under these conditions.

The SN74AUP1T14 is designed with optimized current-drive capability of 4 mA to reduce line reflections, overshoot, and undershoot caused by high-drive outputs.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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NSTRUMENTS

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T _A	PACK	(AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING(3)
4000 to 0500	COT (CC 70) DCK	Reel of 3000	SN74AUP1T14DCKR	c.
–40°C to 85°C	SOT (SC-70) – DCK	Reel of 250	SN74AUP1T14DCKT	6F_

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) The actual top-side marking has one additional character that designates the water fab/assembly site.

FUNCTION TABLE

INPUT (Lower Level Input)	OUTPUT (V _{CC} CMOS)
Α	Y
Н	L
L	Н

Supply $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V } (2.5 \text{ V})$

117	00	<u> </u>
INF V _{T+} max V _{T-} min	OUTPUT CMOS	
Α	В	Y
V _{IH} =	= 1.1 V	V _{OH} = 1.85 V
V _{IL} =	0.35 V	$V_{OL} = 0.45 \text{ V}$

Supply $V_{CC} = 3 \text{ V to } 3.6 \text{ V } (3.3 \text{ V})$

INP V _{T+} max V _{T-} min =	OUTPUT CMOS			
Α	В	Y		
V _{IH} =	V _{IH} = 1.19 V			
V _{IL} =	0.5 V	$V_{OL} = 0.45 \text{ V}$		

LOGIC DIAGRAM (SCHMITT-TRIGGER INVERTER GATE)



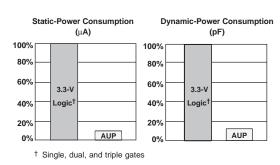


Figure 1. AUP - The Lowest-Power Family

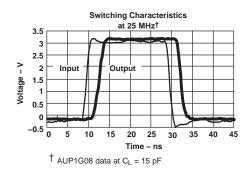


Figure 2. Excellent Signal Integrity

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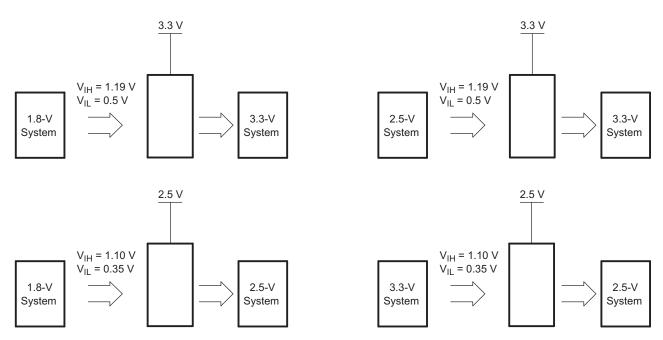


Figure 3. Typical Design Examples

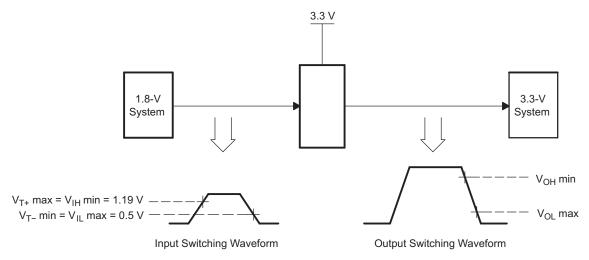


Figure 4. Switching Thresholds for 1.8-V to 3.3-V Translation



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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Voltage range applied to any output in the high-impedance or power	er-off state ⁽²⁾	-0.5	4.6	V
Vo	Output voltage range in the high or low state (2)	-0.5	$V_{CC} + 0.5$	V	
I _{IK}	Input clamp current	V ₁ < 0		- 50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±20	mA
	Continuous current through V _{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance (3)	DCK package		259	°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
V_{I}	Input voltage		0	3.6	V
Vo	Output voltage		0	V_{CC}	V
	High level entropy and	V _{CC} = 2.3 V		-3.1	A
Іон	High-level output current	V _{CC} = 3 V		-4	mA
	Lour lovel output ourrent	V _{CC} = 2.3 V		3.1	A
IOL	Low-level output current	V _{CC} = 3 V		4	mA
T _A	Operating free-air temperature	·	-40	85	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PAF	RAMETER	TEST CONDITIONS	V _{cc}	T _A =	= 25°C	T _A = -40 to 85°C		UNIT
				MIN	TYP MAX	MIN	MAX	
V _{T+}			2.3 V to 2.7 V	0.6	1.1	0.6	1.1	
	e-going input old voltage		3 V to 3.6 V	0.75	1.16	0.75	1.19	V
V _T			2.3 V to 2.7 V	0.35	0.6	0.35	0.6	
	ve-going nreshold e		3 V to 3.6 V	0.5	0.85	0.5	0.85	V
ΔV_{T}			2.3 V to 2.7 V	0.23	0.6	0.1	0.6	
Hyster (V _{T+} -			3 V to 3.6 V	0.25	0.56	0.15	0.56	V
		I _{OH} = -20 μA	2.3 V to 3.6 V	V _{CC} - 0.1		V _{CC} - 0.1		
		$I_{OH} = -2.3 \text{ mA}$	2.3 V	2.05		1.97		V
V_{OH}		I _{OH} = -3.1 mA	2.3 V	1.9		1.85		
		$I_{OH} = -2.7 \text{ mA}$	3 V	2.72		2.67		
		$I_{OH} = -4 \text{ mA}$	3 V	2.6		2.55		
		I _{OL} = 20 μA	2.3 V to 3.6 V		0.1		0.1	
		I _{OL} = 2.3 mA	2.3 V		0.31		0.33	
V_{OL}		I _{OL} = 3.1 mA	2.3 V		0.44		0.45	V
		I _{OL} = 2.7 mA	3 V		0.31		0.33	
		I _{OL} = 4 mA	3 V		0.44		0.45	
I	All inputs	V _I = 3.6 V or GND	0 V to 3.6 V		0.1		0.5	μΑ
$I_{\rm off}$		V_I or $V_O = 0$ V to 3.6 V	0 V		0.1		0.5	μΑ
ΔI_{off}		V_I or $V_O = 3.6 \text{ V}$	0 V to 0.2 V		0.2		0.5	μΑ
I _{CC}		V _I = 3.6 V or GND, I _O = 0	2.3 V to 3.6 V		0.5		0.9	μΑ
		One input at 0.3 V or 1.1 V, Other inputs at 0 or V_{CC} , $I_{O} = 0$	2.3 V to 2.7 V				4	μА
ΔI _{CC}		One input at 0.45 V or 1.2 V, Other inputs at 0 or V_{CC} , $I_{O} = 0$	3 V to 3.6 V			1		μΑ
C_{i}		$V_I = V_{CC}$ or GND	3.3 V		1.5			pF
Co		V _O = V _{CC} or GND	3.3 V		3			pF

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V, V_I = 1.8 V ± 0.15 V (unless otherwise noted) (see Figure 5)

PARAMETER	FROM	TO (OUTPUT)			Т,	_{\(\)} = 25°C	;	T _A = -40°C to 85°C		UNIT
	(INPUT)			MIN	TYP	MAX	MIN	MAX		
t _{pd}	А		5 pF	1.8	2.3	2.9	0.5	6.8		
		V	10 pF	2.3	2.8	3.4	1	7.9		
		Y	15 pF	2.6	3.1	3.8	1	8.7	ns	
			30 pF	3.8	4.4	5.1	1.5	10.8		

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V, V_I = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 5)

PARAMETER	PARAMETER	FROM	TO (OUTPUT)		CL	T	λ = 25°C		T _A =	40°C 5°C	UNIT
	(INPUT)	(OUTPUT)	_	MIN	TYP	MAX	MIN	MAX			
t _{pd}	А	A Y	5 pF	1.8	2.3	3.1	0.5	6			
			10 pF	2.2	2.8	3.5	1	7.1			
			15 pF	2.6	3.2	5.2	1	7.9	ns		
			30 pF	3.7	4.4	5.2	1.5	10			

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V, V_I = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 5)

PARAMETER		TO (OUTPUT)		CL	Т,	_A = 25°C		T _A = -	40°C 5°C	UNIT
			_	MIN	TYP	MAX	MIN	MAX		
t _{pd}		Y	5 pF	2	2.7	3.5	0.5	5.5		
	^		10 pF	2.4	3.1	3.9	1	6.5		
	A		15 pF	2.8	3.5	4.3	1	7.4	ns	
			30 pF	4	4.7	5.5	1.5	9.5		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V, V_I = 1.8 V ± 0.15 V (unless otherwise noted) (see Figure 5)

PARAMETER	FROM	FROM TO (OUTPUT)	CL	Т,	_A = 25°C	;	T _A = -40°C to 85°C		UNIT
	(INPUT)		-	MIN	TYP	MAX	MIN	MAX	
t _{pd}	А		5 pF	1.6	2	2.5	0.5	8	
		V	10 pF	2	2.4	2.9	1	8.5	
		A Y	15 pF	2.3	2.8	3.3	1	9.1	ns
			30 pF	3.4	3.9	4.4	1.5	9.8	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_{I} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 5)

PARAMETER		TO (OUTPUT)		CL	T	λ = 25°C		T _A =	40°C 5°C	UNIT
				MIN	TYP	MAX	MIN	MAX		
t _{pd}	А	A Y	5 pF	1.6	1.9	2.4	0.5	5.3		
			10 pF	2	2.3	2.7	1	6.1		
			15 pF	2.3	2.7	3.1	1	6.8	ns	
			30 pF	3.4	3.8	4.2	1.5	8.5		

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V, V_I = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 5)

PARAMETER	FROM	TO (OUTPUT)	CL	T	λ = 25°C		T _A =	40°C 5°C	UNIT
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	
			5 pF	1.6	2.1	2.7	0.5	4.7	
4	^	V	10 pF	2	2.4	3	1	5.7	
t _{pd}	A	ř	15 pF	2.3	2.7	3.3	1	6.2	ns
			30 pF	3.4	3.8	4.4	1.5	7.8	

OPERATING CHARACTERISTICS

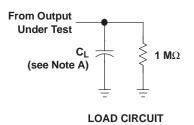
 $T_A = 25^{\circ}C$

	PARAMETER TEST CONDITIONS $V_{CC} = 2.5 \text{ V}$ $V_{CC} = 3.3 \text{ V}$ TYP TYP Power dissipation capacitance $f = 10 \text{ MHz}$ 4 5	V _{CC} = 3.3 V	UNIT			
	PARAMETER	TEST CONDITIONS	TYP	TYP	ONIT	
C_{pd}	Power dissipation capacitance	f = 10 MHz	4	5	pF	

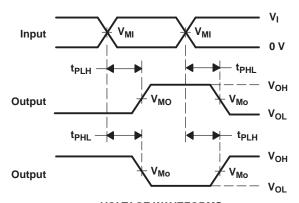
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PARAMETER MEASUREMENT INFORMATION



	V _{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V \pm 0.3 V
C _L	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V _{MI}	V _I /2	V _I /2
V _{MO}	V _{CC} /2	V _{CC} /2



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \ \Omega$, slew rate \geq 1 V/ns.
- C. The outputs are measured one at a time, with one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 5. Load Circuit and Voltage Waveforms

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PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74AUP1T14DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6FF	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1T14DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

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*All dimensions are nominal

Device	evice Package Type		Package Drawing Pins S			Width (mm)	Height (mm)	
SN74AUP1T14DCKR	SC70	DCK	5	3000	180.0	180.0	18.0	



SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.
- 5. Lead width does not comply with JEDEC.
- 6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 10. Board assembly site may have different recommendations for stencil design.



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